



Thematic Network on Silicon on Insulator Technology, Devices and Circuits.
[IST-1-506653-CA]

EUROSIO "Who is Who" Guide

Name of the organisation

<i>Organization Legal name:</i>	Institut fuer Mikroelektronik Stuttgart
<i>Organization short name:</i>	IMS-Chips
<i>Internet homepage:</i>	www.ims-chips.de

Contact person

<i>Name:</i>	<i>Appel</i>	<i>Title:</i>	<i>Dr.</i>
<i>First name:</i>	<i>Wolfgang</i>	<i>Sex:</i>	<i>male</i>
<i>Phone:</i>	<i>+49 711 21855 400</i>	<i>E-mail:</i>	<i>appel@ims-chips.de</i>
<i>Postal Address</i>	<i>Allmandring 30a, 70569 Stuttgart, Germany</i>		

Other Senior Researchers: (up to 10 names, please include e-mail address)

Dr. Christine Harendt, Harendt@ims-chips.de
Dr. Jörg Butschke, butschke@ims-chips.de
Dr. Florian Letzkus, Letzkus@ims-chips.de

Experience and expertise fields: (50 words)

Wafer bonding, membrane etching, deep trench etching, epitaxy on porous silicon, buried silicide, stress engineering in SOI-film

Facilities and Equipment:

Suess Bond Aligner, STS Trench Etcher, KOH wet etching, e-beam direct writer, CMOS equipment

Three last international research projects:

Hiperlogic (EC), Ion Projection Lithography (MEDEA), ISOSURF (BMBF), ILIAS (BMBF)